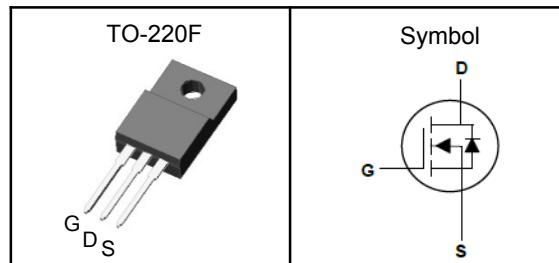


N-Channel Enhancement Mode MOSFET

Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant
- 100% UIS and Rg Tested

Pin Description



Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC to DC Converters

V_{DSS}	500	V
$R_{DS(ON)-Typ}$	180	$\text{m}\Omega$
I_D	20	A

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit	
V_{DSS}	Drain-Source Voltage	500	V	
V_{GSS}	Gate-Source Voltage	± 30	V	
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
E_{AS}	Single Pulse Avalanche Energy ^③	1500	mJ	
$I_{DM}^{①}$	Pulse Drain Current Tested	100	A	
I_D	Continuous Drain Current	$T_c=25^\circ\text{C}$	20	A
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	50	W

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{θJA}$	Thermal Resistance Junction-Ambient ^①	62.5	$^\circ\text{C}/\text{W}$
$R_{θJC}$	Thermal Resistance Junction-Case ^①	2.5	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C .

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

N-Channel Enhancement Mode MOSFET
Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

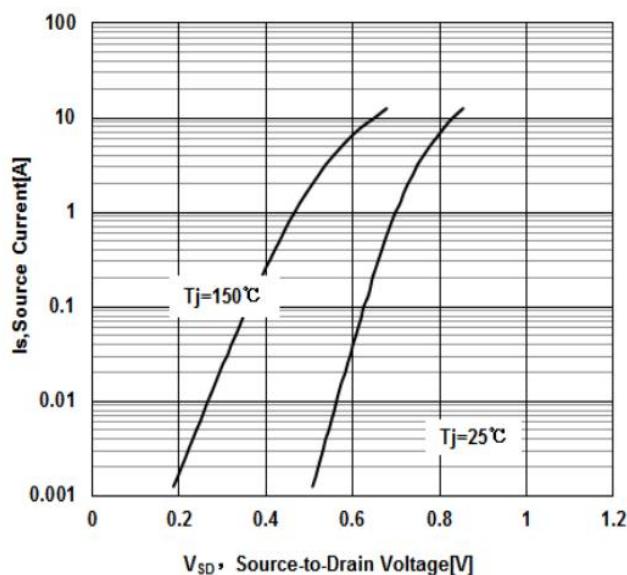
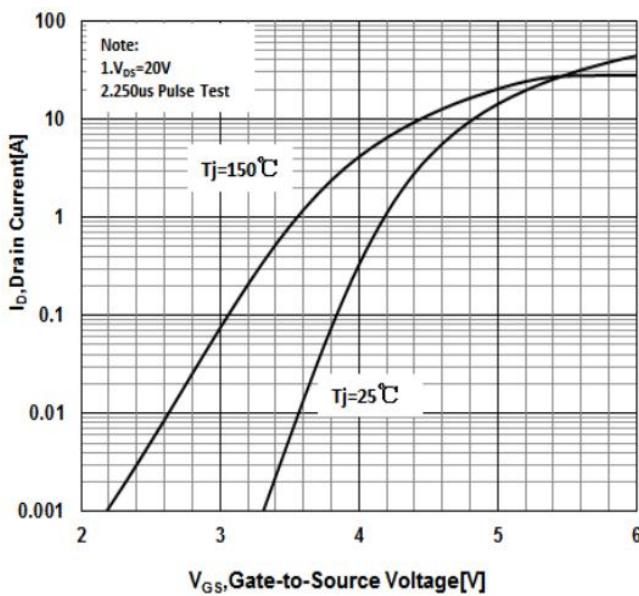
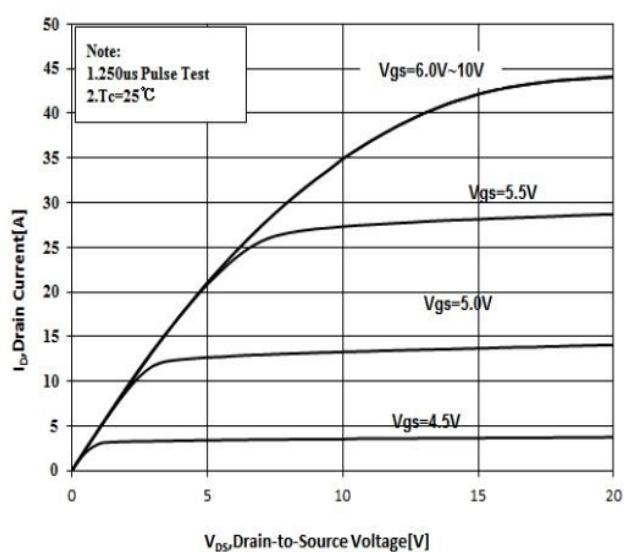
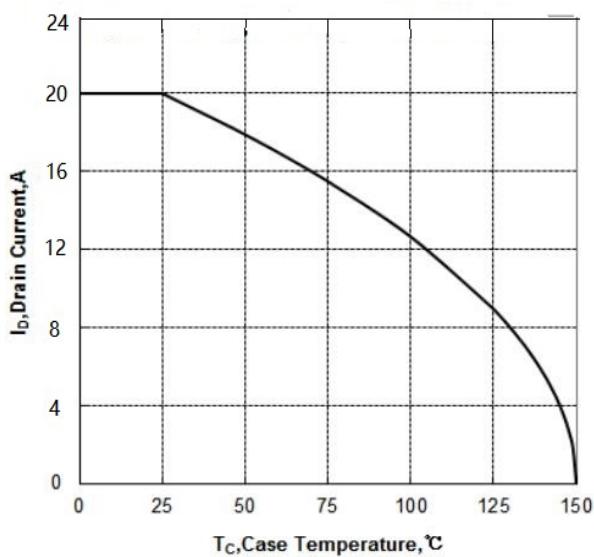
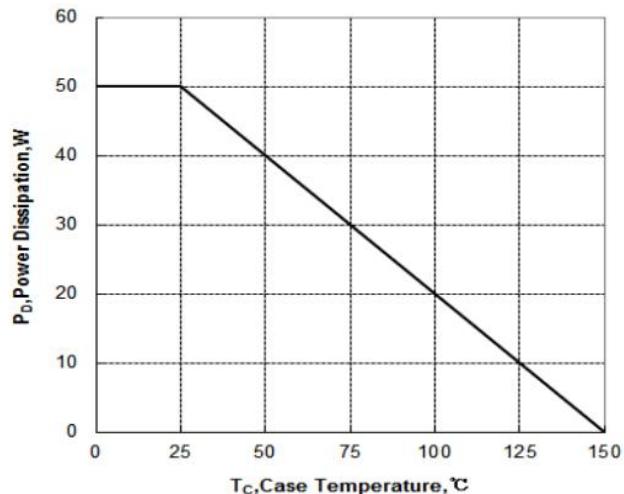
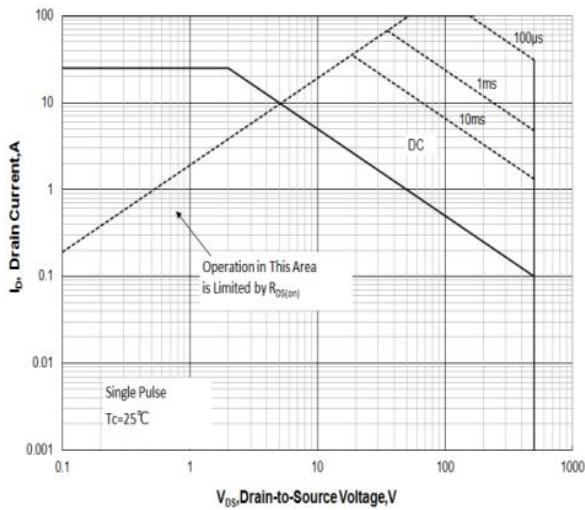
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	500	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=500\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	1	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	2.0	---	4.0	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 30\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=12.5\text{A}$	---	180	210	$\text{m}\Omega$
Dynamic Characteristics ^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=25\text{V}$, Freq.=1MHz	---	3482	---	pF
C_{oss}	Output Capacitance		---	210	---	
C_{rss}	Reverse Transfer Capacitance		---	11	---	
$T_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=250\text{V}$, $R_G=10\Omega$, $I_D=20\text{A}$	---	37	---	nS
T_r	Turn-on Rise Time		---	65	---	
$T_{\text{d(off)}}$	Turn-off Delay Time		---	86	---	
T_f	Turn-off Fall Time		---	46	---	
Q_g	Total Gate Charge	$V_{\text{DD}}=400\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=20\text{A}$	---	64.3	---	nC
Q_{gs}	Gate-Source Charge		---	16.7	---	
Q_{gd}	Gate-Drain Charge		---	23	---	
Source-Drain Characteristics ($T_J=25^\circ\text{C}$)						
V_{SD}	Diode Forward Voltage ^②	$V_{\text{GS}}=0\text{V}$, $I_S=20\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.5	V
t_{rr}	Reverse Recovery Time	$I_S=20\text{A}$, $di/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	487	---	nS
Q_{rr}	Reverse Recovery Charge		---	6235	---	nC

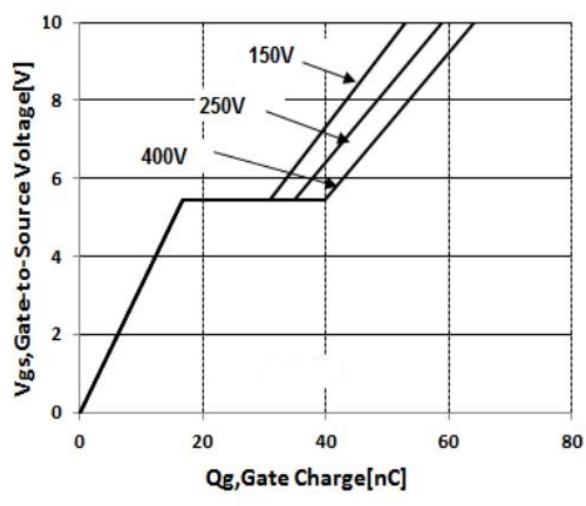
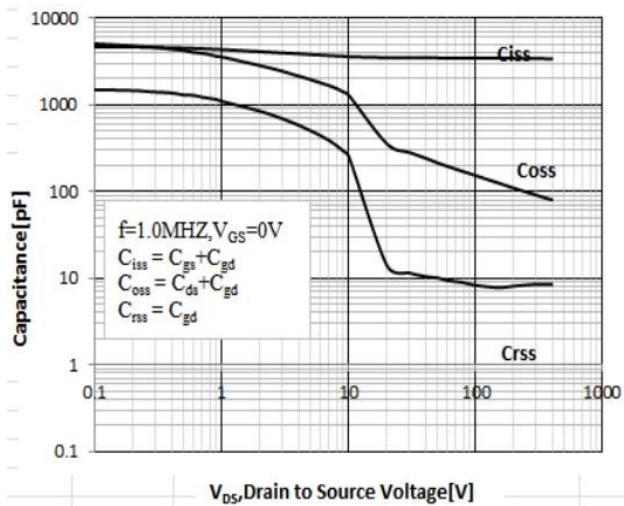
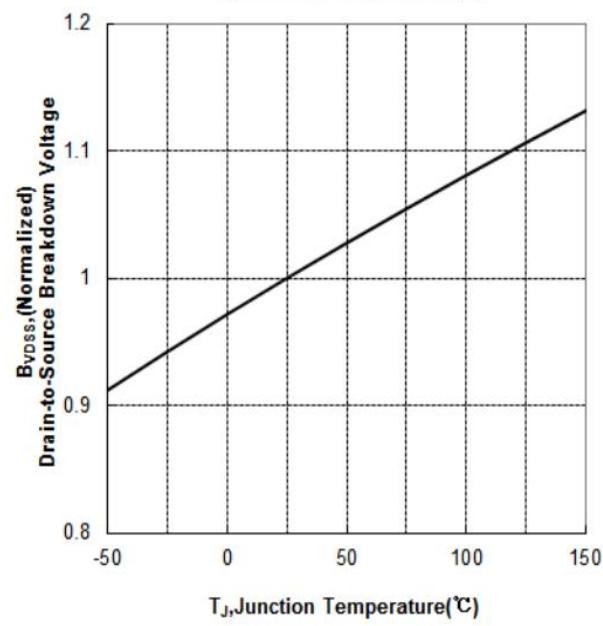
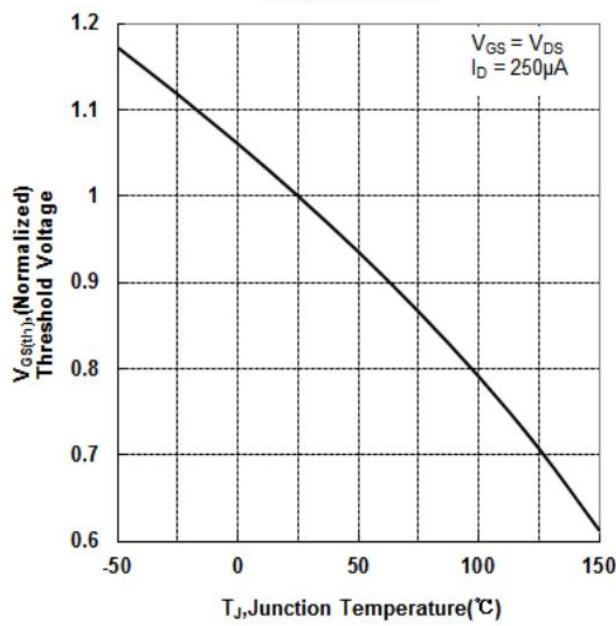
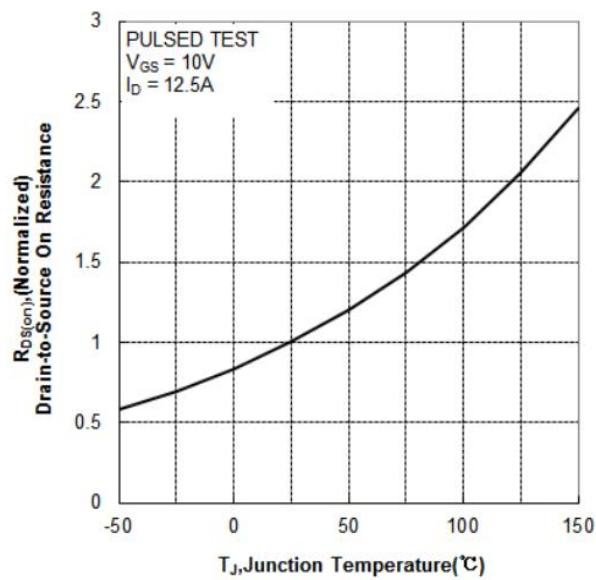
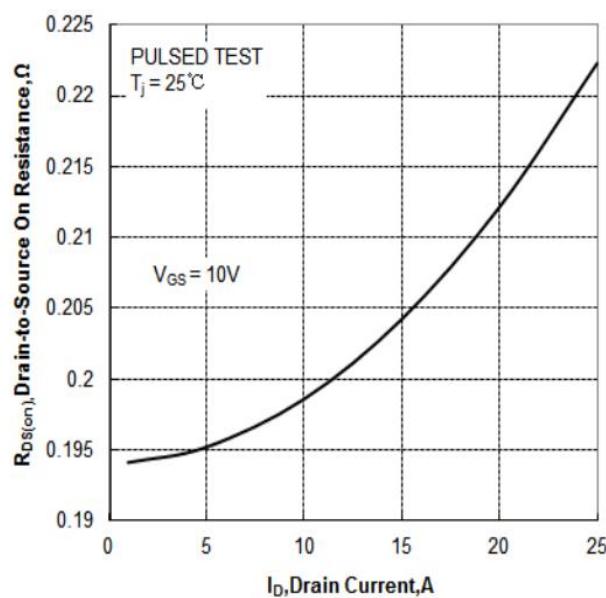
Note ④ : Pulse test (pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

N-Channel Enhancement Mode MOSFET

Typical Characteristics



N-Channel Enhancement Mode MOSFET


N-Channel Enhancement Mode MOSFET

TO-220F Package Outline Data

